

## TD051SCANH3 SOIC package isolated CAN Transceiver

### Features

- Ultra-small, ultra-thin, chip scale SOIC package
- Compliant with ISO11898-2 standard
- I/O power supply range supports 3.3V and 5V microprocessors
- High isolation to 5000VAC
- Bus-Pin ESD protection up to 8kV(HBM)
- Baud rate up to 5Mbps
- -40V to 40V bus fault protection
- >180kV/ $\mu$ s CMTI
- TXD dominant time-out function
- Low loop delay
- The bus supports maximum 110 nodes
- Industrial operating ambient temperature range: -40°C to +125°C
- Moisture Sensitivity Level (MSL) 3

### Package



### Applications

- Industrial automation, control, sensors and drive systems
- Building and greenhouse environmental control(HVAC) automation
- Security system
- Transport
- Medical treatment
- Telecommunication
- CAN Bus standard such as CAN open, Device Net, NMEA2000, ARNIC825, ISO11783, CAN Kingdom, CAN aerospace

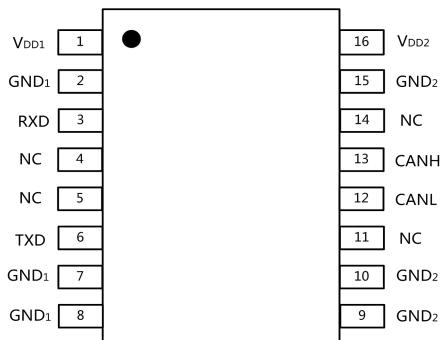
### Functional Description

The TD051SCANH3 is an isolated CAN transponder that meets or exceeds the specifications of the ISO11898-2 standard. As a CAN transceiver, the device provides differential transmit and receive capability for the bus and CAN controller, respectively. It is capable of running at data rates of up to 5Mbps. Particularly suited for harsh environments, the device features protection against cross-wire, overvoltage, and ground loss (-40V to 40V), as well as thermal shutdown. The TD051SCANH3 is rated for operation over the -40°C to 125°C ambient temperature range.

## Contents

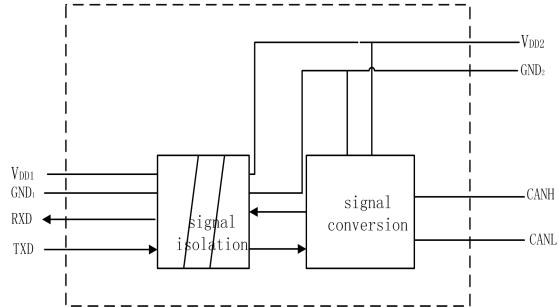
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### Pin Connection



Note: All GND1 pins are internally connected;  
All GND2 pins are internally connected..

### Internal Block Diagram



### Function Table

Letter	Description
H	High-Level
L	Low-Level
I	Uncertainty
X	Unrelated
Z	High Impedance
NC	Connectionless

Table 1. Driver Function table

Supply status		Input	Output		
V <sub>DD1</sub>	V <sub>DD2</sub>		State	CANH	CANL
On	On	L	Dominant	H	L
On	On	H	Recessive	Z	Z
On	On	vacant	Recessive	Z	Z
Off	On	X	Recessive	Z	Z
On	Off	L	I	I	I

Table 2. Receiver Function table

Supply status		Input	Output	
V <sub>DD1</sub>	V <sub>DD2</sub>	V <sub>ID</sub> = CANH – CANL	Bus Status	RXD
On	On	≥0.9 V	Dominant	L
On	On	≤0.5 V	Recessive	H
On	On	0.5 V < V <sub>ID</sub> < 0.9 V	I	I
On	On	Input open circuit	Recessive	H
Off	On	X	X	I
On	Off	X	X	H

## Pin Descriptions

Pinout	Markings	Functionality
1	V <sub>DD1</sub>	Power supply for the console.
2	GND <sub>1</sub>	Console Ground.
3	RXD	CAN receiver outputs (L: bus state is explicit; H: bus state is implicit).
4	NC	No function pins, can be dangled.
5	NC	No function pins, can be dangled.
6	TXD	CAN driver input (L: bus state is explicit; H: bus state is implicit).
7	GND <sub>1</sub>	Console Ground.
8	GND <sub>1</sub>	Console Ground.
9	GND <sub>2</sub>	Bus End Ground.
10	GND <sub>2</sub>	Bus End Ground.
11	NC	No function pins, can be dangled.
12	CANL	Low-potential CAN voltage inputs and outputs.
13	CANH	High-potential CAN voltage inputs and outputs.
14	NC	No function pins, can be dangled.
15	GND <sub>2</sub>	Bus End Ground.
16	V <sub>DD2</sub>	Bus-side power supply.

## Absolute Maximum Ratings

General test conditions: Free-air, normal operating temperature range (unless otherwise specified).

Parameters		Min.	Max.	Unit
V <sub>DD1</sub> , V <sub>DD2</sub>	Supply Voltage	-0.5	6	V
V <sub>I</sub>	Input Voltage (TXD)	-0.5	V <sub>DD1</sub> + 0.5	V
V <sub>O(RXD)</sub>	Output Voltage (RXD)	-0.5	V <sub>DD1</sub> + 0.5	V
V <sub>O(SENSE)</sub>	Output Voltage (V <sub>DD2SENSE</sub> )	-0.5	V <sub>DD1</sub> + 0.5	V
V <sub>CANH</sub> , V <sub>CANL</sub>	Arbitrary bus terminal voltage (CANH, CANL)	-40	40	V
V <sub>REF</sub>	Reference Voltage Output Value	-0.5	+6	V
T <sub>A</sub>	Operating temperature range	-40	125	°C
T <sub>stg</sub>	Storage temperature range	-65	150	°C
Reflow temperature		Peak temperature T <sub>c</sub> ≤ 260°C, time above 217°C max. 60s. For practical application, please refer to IPC/JEDEC J-STD-020D.3 standard.		

Important: Exposure to absolute maximum rated conditions for an extended period may severely affect the device reliability, and stress levels exceeding the "Absolute Maximum Ratings" may result in permanent damage. All voltage values are based on the reference ground(GND) maximum voltage not exceeding 6V.

## Recommended Operating Conditions

Parameters			Min.	Typ.	Max.	Unit	
V <sub>DD1</sub>	Supply voltage (control terminal)		2.375	3.3	5.5	V	
V <sub>DD2</sub>	Supply voltage (bus terminals)		4.5	5	5.5	V	
V <sub>I</sub> or V <sub>IC</sub>	Bus Input Pin Withstand Voltage (Common Mode)			-40		40	V
V <sub>IH</sub>	TXD high input voltage			2			V
V <sub>IL</sub>	TXD low input voltage				0.8		V
I <sub>VDD1_S</sub>	Console input quiescent current	V <sub>DD1</sub> = 5.5V, V <sub>DD2</sub> = 5.5V,no signal		3.7	6	mA	
I <sub>VDD2_S</sub>	Bus End input quiescent current			5.5	10		
I <sub>VDD1_D</sub>	Console dynamically sends current	V <sub>DD1</sub> = 5.5V, V <sub>DD2</sub> = 5.5V,RL= 60Ω; TXD Pin Input Signal : f=500kHz; Duty=50%		3.5	6	mA	
I <sub>VDD2_D</sub>	Bus End dynamically sends current			38	50		
P <sub>D</sub>	Total power dissipation	V <sub>DD1</sub> = 5.5V, V <sub>DD2</sub> = 5.25V, TA=105°C, RL= 60Ω; TXD Pin Input Signal : f=500kHz ; Duty=50%			300	mW	
P <sub>D1</sub>	Console power dissipation				30		
P <sub>D2</sub>	Power Dissipation on Power Side				275		
	transmission rate				5000	kbps	

## Electrical Characteristics

General test conditions and V<sub>CC</sub>=V<sub>IO</sub>= 5V, Ta = 25°C (unless otherwise specified).

Parameters		Conditions	Min.	Typ.	Max.	Unit
<b>Drives</b>						
V <sub>IH</sub>	Logic Input High	TXD Pinout, Figure11	2			V
V <sub>IL</sub>	Logic Input Low	TXD Pinout,Figure11			0.8	V
I <sub>IH</sub> , I <sub>IL</sub>	CMOS Logic Input Current	TXD Pinout,Figure 11			20	uA
V <sub>CANL</sub> ,V <sub>CANH</sub>	Implicit differential output bus voltage	V <sub>TXD</sub> = high, R <sub>L</sub> = ∞,Figure 11	2.0		3.0	V
V <sub>CANH</sub>	CANH dominant differential output bus voltage	V <sub>TXD</sub> = low, Figure11	2.75		4.5	V
V <sub>CANL</sub>	CANL dominant differential output bus voltage	V <sub>TXD</sub> = low, Figure11	0.5		2	V
V <sub>OD</sub>	Differential Output Voltage	V <sub>TXD</sub> = low, R <sub>L</sub> = 50 Ω, Figure 11	1.5		3	V
		V <sub>TXD</sub> = high, R <sub>L</sub> = ∞, Figure 11	-50		+50	mV
<b>Receiver</b>						
V <sub>IT+</sub>	Positive Input Threshold				900	mV
V <sub>IT-</sub>	Negative Input Threshold		500			mV
V <sub>HYS</sub>	Hysteresis voltage (VIT+ - VIT-)	Figure 14		150		mV
R <sub>DIFF</sub>	Bus differential input impedance		10		100	kΩ
V <sub>OL</sub>	Logic output low	I <sub>OUT</sub> = 1.5 mA		0.2	0.4	V
V <sub>OH</sub>	Logic Output High	I <sub>OUT</sub> = -1.5 mA	V <sub>DD1</sub> - 0.4	V <sub>DD1</sub> - 0.2		V
<b>Other</b>						
ESD	HBM Mode	CANH, CANL pins to GND			±8	kV
	Contact IEC61000-4-2 : Perf. Criteria B	CANH, CANL			±4	kV
V <sub>I-O</sub>	Isolated Withstand Voltage	Input-Output, Leakage current<1mA Rise time 3s, Fall time 1s	5000			VAC
R <sub>I-O</sub>	Insulation impedance	500VDC	1000			MΩ
CMTI	common mode transient immunity	TXD = V <sub>DD1</sub> or 0 V, V <sub>CM</sub> = 1 kV, transient magnitude = 800 V		180		kV/μs

## Transmission Characteristics

Parameters		Conditions	Min.	Typ.	Max.	Unit	
$t_{LOOP1}$ $t_{LOOP2}$		Loop delay ( TXD input to RXD output )	Figure 15		160	200	ns
Driver Characteristics							
$t_{PLHD}$	TXD propagation delay time ( TXD input to bus dominant output )	Figure 13		75	100	ns	
$t_{PHLD}$	TXD propagation delay time ( TXD input to bus recessive output )			85	100	ns	
$t_r, t_f$	Differential output signal rise,fall time			30	60	ns	
$t_{TXD\_DTO}$	Bus dominant time-out time		0.3		5	ms	
Receiver Characteristics							
$t_{PLHR}$	RXD propagation delay time ( Bus recessive to RXD output )	Figure 14		85	130	ns	
$t_{PHLR}$	RXD propagation delay time ( Bus dominant to RXD output )			85	130	ns	
$t_r, t_f$	RXD signal rise,fall time			2.5	6	ns	

## Physical Specifications

Parameters	Value	Unit
Weight	0.4(Typ.)	g

## Test Circuits

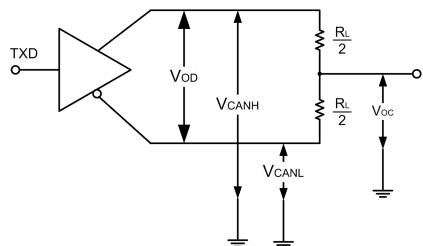


Figure 11. Driver test circuit

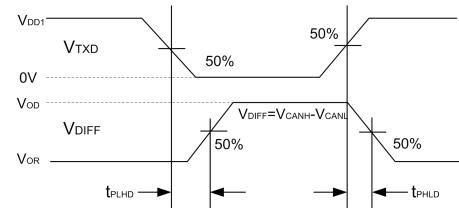


Figure 12. Drive and propagation delay waveform

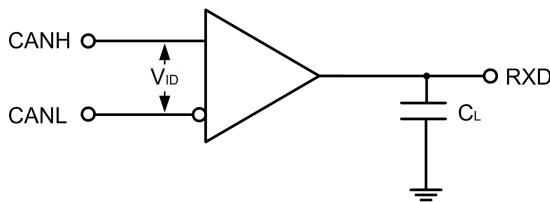


Figure 13. Receiver test circuit

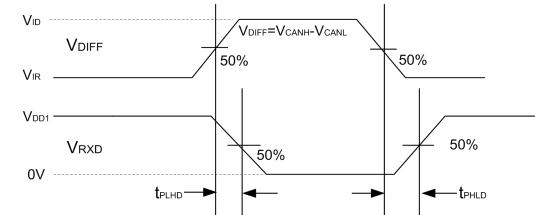


Figure 14. Receiver propagation delay waveform

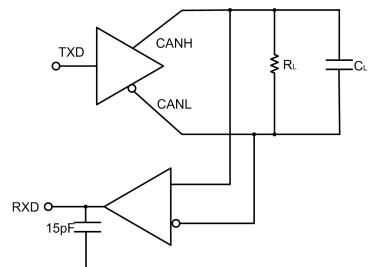


Figure 15. Propagation test circuit

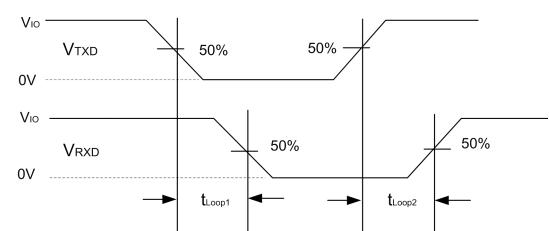


Figure 16. Loop delay waveform

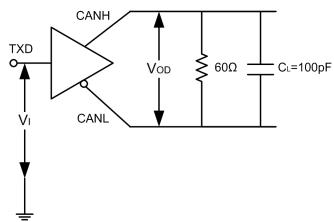


Figure 17. Dominant Time-out test circuit

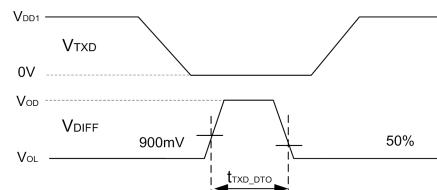


Figure 18. Dominant Time-out waveform

## Detailed Description

TD051SCANH3 is a CAN of a style of separation transceiver with the ability of differential signal transmission between the bus and CAN protocol controller, it the inner integration insulate DC/DC power supply which is compliant with ISO11898-2 standard.

**Short-circuit protection:** TD051SCANH3 has current-limiting protection to prevent the drive circuit from short-circuiting to positive and negative supply voltages. The power dissipation increases when a short circuit occurs. The short-circuit protection function protects the driver stage from damage.

**Over-temperature protection:** TD051SCANH3 has over-temperature protection. After over-temperature protection is triggered the current in the driver stage will decrease. Because the drive tube is the primary energy consuming component, current reduction can reduce power consumption and reduce chip temperature. At the same time, the rest of the chip remains functional.

**Dominant time-out function:** TD051SCANH3 has dominant time-out function to prevent if the pin TXD is forced to a permanent low level due to a hardware or software application failure, the built-in TXD dominant timeout timer circuit prevents the bus line from being driven to a permanent dominant state (blocking all network traffic). The timer is triggered by the negative edge on pin TXD, If the low level on pin TXD lasts longer than the internal timer value ( $t_{TXD\_DTO}$ ), the transmitter will be disabled and the drive bus will enter a recessive state. The timer is reset by the positive edge on pin TXD.

## Application circuit

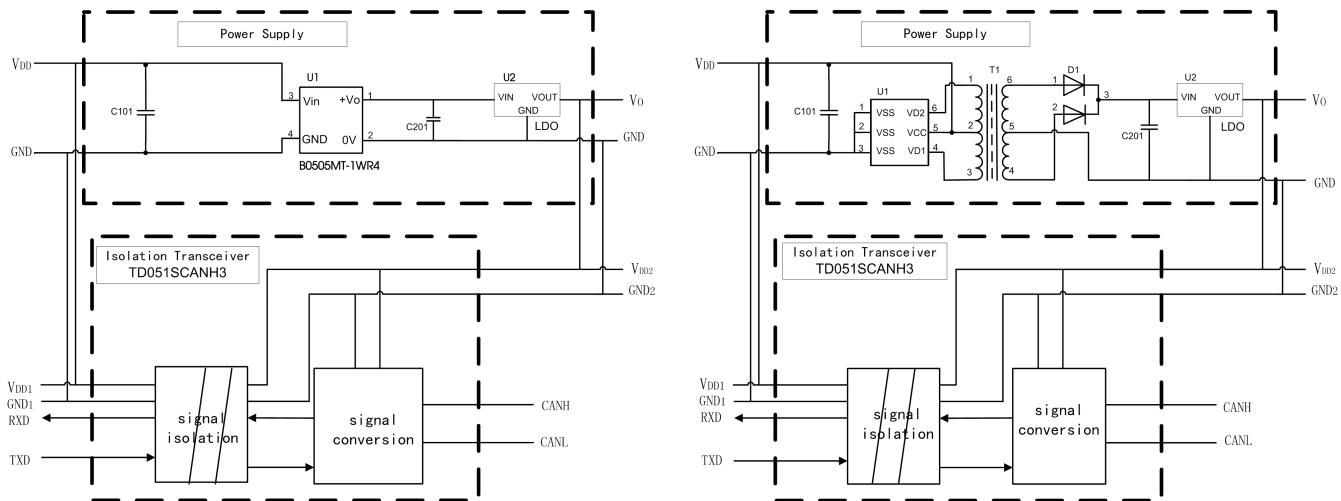


Figure19. Typical application circuit

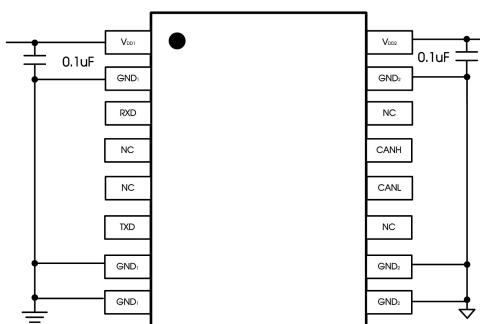


Figure20. Typical Application of PCB layout

## Recommendations for use

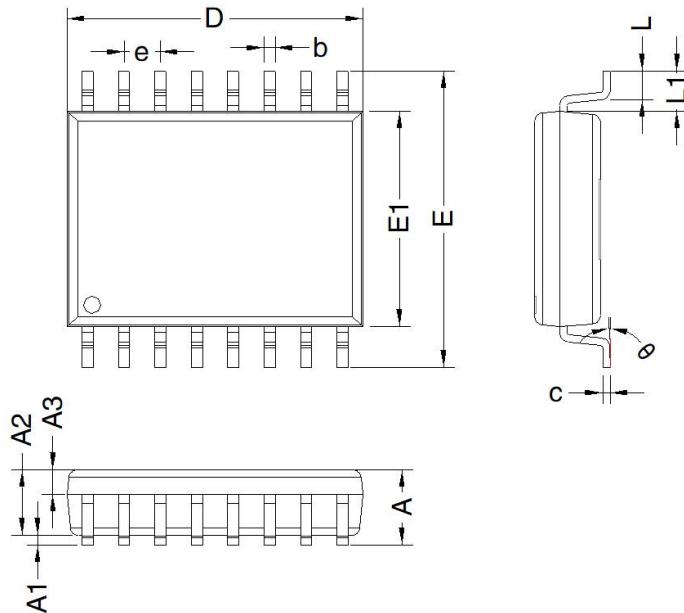
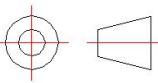
- ① Hot-swap is not supported.
- ② If the external input of TXD is insufficient, the pull-up resistor should be added according to the situation.

## Ordering Information

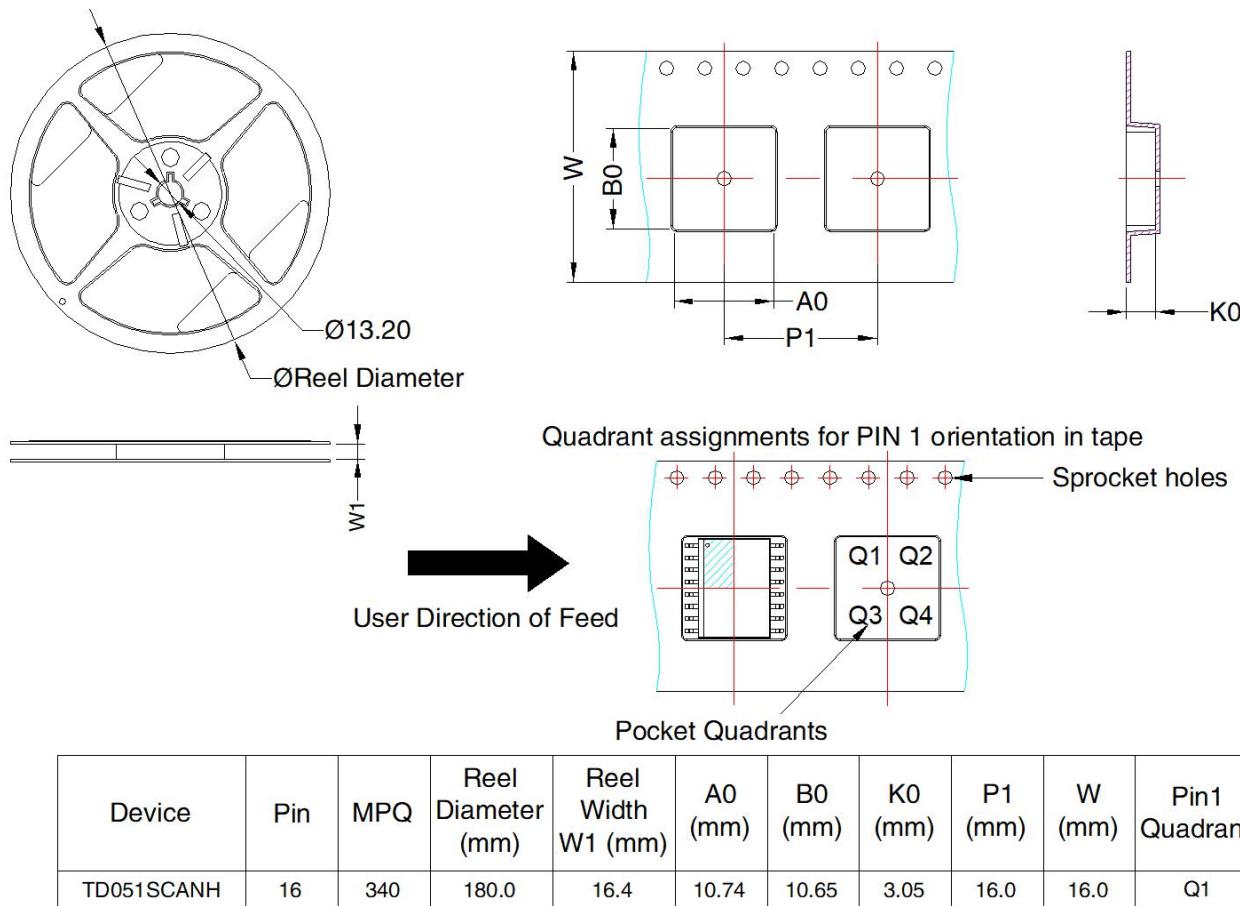
Part number	Package	Number of pins	Product marking	Tape & Reel
TD051SCANH3	SOIC	16	TD051SCANH3	340/RELL

## Package Information

THIRD ANGLE PROJECTION



Mark	Dimension(mm)	
	Min	Max
A	-	2.65
A1	0.10	0.30
A2	2.25	2.35
A3	0.97	1.07
b	0.35	0.43
c	0.24	0.29
D	10.20	10.40
e	1.27 BSC	
E	10.10	10.50
E1	7.40	7.60
L	0.55	0.85
L1	1.40 BSC	
θ	0°	8°



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